

Process for Producing Adhesive Sheet Having Singulated Adhesive Layer, Process
for Producing Wiring Substrate Using the Adhesive Sheet, Method of Manufacturing
Semiconductor Equipment, and Equipment for Producing Adhesive Sheet

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ABSTRACT

Provided is a process for producing an adhesive sheet having a singulated
adhesive layer (b) on a carrier film (a), comprising the following steps in the order
mentioned:

Step A: cutting an adhesive film having a carrier film (a), an adhesive layer (b), and a
10 cover film (c) in the order mentioned locally only at the adhesive layer (b) and the
cover film (c) by means of local half-cutting;

Step B: peeling only the cover film (c) at unwanted parts of the adhesive film;

Step C: applying adhesive tape to the side of the cover film (c) of the adhesive film;
and

15 Step D: peeling the adhesive layer (b) at unwanted parts and the cover film (c) at
desired parts of the adhesive film together with the adhesive tape.

Also provided are a process for producing an adhesive sheet comprising a
singulated adhesive disposed at a specific position, and equipment for producing an
adhesive sheet.

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Figure 7

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